Abstract

An automated method of injecting polymer onto a substrate using a controllable back plate to move said substrate to desire location for applying the polymer whereas the integrated pressure system delivers a predetermined amount of the polymeric material through a chilled transfer line adapted through a set of insulated die press members and a set of heated die press member where a necessary amount of heat is transferred to raise the temperature of the previously chilled polymeric material to a specified curing temperature, applying to the substrate, and consequentially providing an adhesive bond for said polymeric material to attach to the substrate without requiring a seal to be made between the die members and the substrate and a curing time to the process.